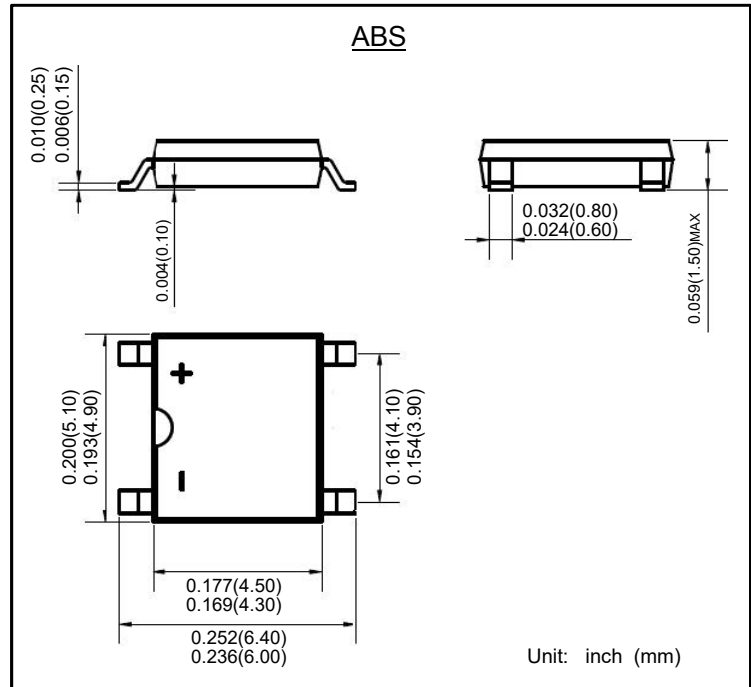


Features

- Low reverse leakage
- High forward surge capability
- High temperature soldering guaranteed:
260°C/10seconds
- Glass passivated chip
- Lead and body according with RoHS standard

Mechanical Data

- Case: ABS Molded plastic
- Polarity: Symbols molded or marked on body
- Mounting Position: Any



Maximum Ratings & Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

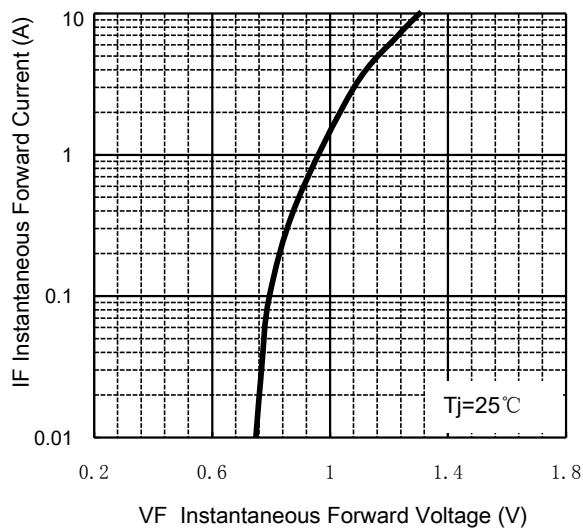
Parameter	Symbols	ABS02	ABS04	ABS06	ABS08	ABS10	Unit
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	200	400	600	800	1000	V
Maximum average forward rectified current	$I_{F(AV)}$	0.8					A
Non-repetitive peak forward surge current 10 ms singlehalf sine-wave	I_{FSM}	30					A
@ $I_F=0.4A$ Maximum forward voltage	V_F	1.10					V
@ V_{DC} Maximum reverse current	I_R	10					μA
$T_A=25^\circ C$		100					
Typical thermal resistance (Note 1)	$R_{\theta JA}$	70					$^\circ C/W$
Typical thermal resistance (Note 1)	$R_{\theta JL}$	20					
$V_R=4.0V, f=1MHz$ Type junction capacitance	C_j	10					pF
Operating junction and storage temperature rang	T_j, T_{STG}	-55 --- +150					$^\circ C$

Note:

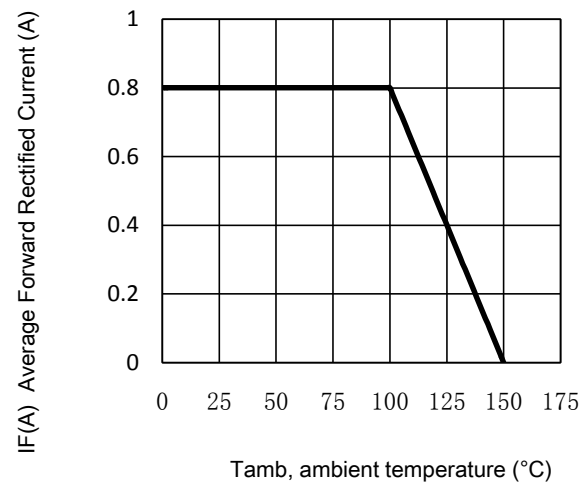
1) Thermal resistance from junction to ambient, PCB mounted.

Characteristic Curves

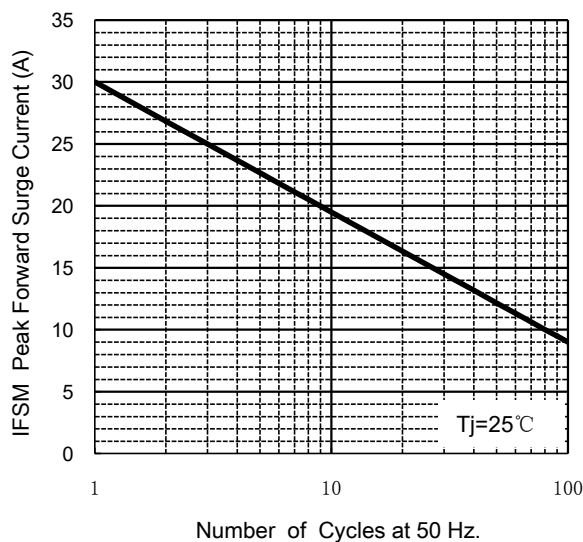
TYPICAL FORWARD CHARACTERISTIC



FORWARD CURRENT DERATING CURVE



MAXIMUM NON REPETITIVE
PEAK FORWARD SURGE CURRENT



Typical Reverse Characteristics

